

AgilBrick™ 2.54mm Board-to-Board Header G800 Series

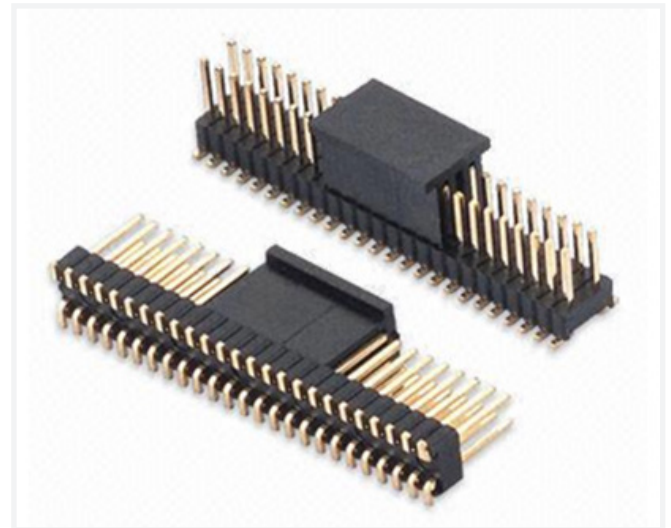
CUSTOMIZABLE UNSHROUDED BOARD-TO-BOARD HEADER

AgilBrick™ 2.54mm Board-to-Board Header G800 Series offers a cost-effective solution with a flexible structure and 1 to 4 A current rating. These headers from Amphenol ICC can be customized to meet various customer requirements. It comes in customizable pin length, including contact pin and solder tail, which makes it an ideal choice for several applications and specific designs. These headers also makes it easier to choose from different board mounting configurations as it supports various mounting options including vertical DIP, right angle DIP, vertical SMT and right angle SMT.

- Flexible and easy to change pin lengths to meet various application requirements
- Cost-effective
- Suitable for both wire-to-board and board-to-board application
- Supports PIP process
- Easy pin insertion and high retention force onto PCB

FEATURES

- Customizable pin length, including contact pin and solder tail
- Various mounting options including vertical DIP, right angle DIP, vertical SMT and right angle SMT
- High temperature thermoplastic material
- Tape and reel packaging option
- Flexible structure
- Available in gold flash, 15u" gold, 30u" gold or tin plating
- RoHS compliant and halogen-free
- Provide longer pin wipe



TARGET MARKETS



BENEFITS

- Suitable for different application and specific designs
- Ease in choosing board mating configurations
- Reflow compatible
- Supports PIP process
- Customizable and cost efficient
- Enhanced reliability and price flexibility
- Meets environmental, health and safety requirements
- Ensures reliable contacts

TECHNICAL INFORMATION

MATERIAL

- Insulator: High temperature thermoplastic material, UL 94V-0 rated
- Contacts: Copper alloy, selective gold plating on contact area
- Shield: Selective gold plated or tin plated on solder tail and nickel plated under-plated overall

ELECTRICAL PERFORMANCE

- Current rating: 3A AC/DC
- Voltage rating: 250V DC
- Temperature: -25°C to +105°C
- Insulation resistance: 1000MΩ min.

MECHANICAL PERFORMANCE

- Contact retention: 1.20kgf min. before solder, 0.90kgf min. after solder
- Durability: 300 cycles
- Contact resistance: $\Delta R=10m\Omega$
- Insertion force: 350g max. per pin
- Withdrawal force: 40g min. per pin

SPECIFICATION

- Amphenol product specification: PS-7501

ENVIRONMENTAL

- EIA 364-31 method III test condition A
- Temperature: 25°C to 65°C
- Humidity: 90% to 95% RH
- Period: 96 hours

PACKAGING

- Operating Procedure: #COP-15-1
- Packing Specification: PKS-0001

TARGET MARKETS/APPLICATIONS



Communications



Portable device



Mother board
Riser card
Signal transmission



POS
Smart meter
Control board



Medical